

Generic Copy

12-May-2010

<u>TITLE</u>: Final Notification for Phase 2 Transfer of Ultrafast Rectifiers from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia)

PROPOSED FIRST SHIP DATE: 12-Aug-2010

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Fab Site

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Raja Roziah Raja Rahmat < Raja.Roziah.Rahmat@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office or Raja Roziah Raja Rahmat < Raja.Roziah.Rahmat@onsemi.com >

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Laura Rivers < laura.rivers@onsemi.com >

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is an FPCN from IPCN 16250 and a follow up to FPCN 16365. ON Semiconductor is notifying customers that these additional Ultrafast Rectifier products will transfer from ON Semiconductor ZR Fab in Phoenix (USA) to ON Semiconductor ISMF Fab in Seremban (Malaysia).

The ISMF facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor since 1998. Several existing technologies within ON Semiconductor's product families are currently sourced from ISMF, including Schottky & Ultrafast Rectifiers, Zener Diodes, Small Signal Transistor, and USB array filter products. ON Semiconductor Seremban Wafer FAB is an internal factory that is TS16949, ISO-9001 and ISO-14000 certified.

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RELIABILITY DATA SUMMARY:

QUALIFICATION PLAN

Reliability testing was performed on qualification vehicles chosen based on die size and voltage rating.

Reliability Test Results:

Package: TO-220AB

Qual Vehicle: MUR1660CTG

Test:	Conditions:	Interval:	Results
HTRB	Ta=150C, 80% rated V	1008 hrs	0/240
AUTOCLAVE	Ta=121C RH=100% ~15 psig	96 hrs	0/240
H3TRB	Ta= 85C RH=85%		
	bias=80% rated V or100V Max	1008 hrs	0/240
IOL	Ta=25C, Delta TJ = 100 C,		
	Ton/off = 3.5 min.	8572 cyc	0/240
TC	Ta= -65 C to 150 C air to air	1000 cyc	0/240
RSH	Ta=260C, 10 sec dwell	post stress	0/30
DPA	AEC Q101-004	post TC	0/6
DPA	AEC Q101-004	post H3TRB	0/6

Package: TO-220AB

Qual Vehicle: MUR1620CTRG

Test:	Conditions:	Interval:	Results
HTRB	Ta=150C, 80% rated V	1008 hrs	0/240
AUTOCLAVE	Ta=121C RH=100% ~15 psig	96 hrs	0/240
H3TRB	Ta= 85C RH=85%		
	bias=80% rated V or100V Max	1008 hrs	0/240
IOL	Ta=25C, Delta TJ = 100 C,		
	Ton/off = 3.5 min.	8572 cyc	0/240
TC	Ta= -65 C to 150 C air to air	1000 cyc	0/240
RSH	Ta=260C, 10 sec dwell	post stress	0/30
DPA	AEC Q101-004	post TC	0/6
DPA	AEC Q101-004	post H3TRB	0/6

Package: TO-220AC Qual Vehicle: MSR1560G

Test:	Conditions:	Interval:	Results
HTRB	Ta=150C, 80% rated V	1008 hrs	0/240
AUTOCLAVE	Ta=121C RH=100% ~15 psig	96 hrs	0/240
H3TRB	Ta= 85C RH=85%		
	bias=80% rated V or100V Max	1008 hrs	0/240
IOL	Ta=25C, Delta TJ = 100 C,		
	Ton/off = 3.5 min.	8572 cyc	0/240
TC	Ta= -65 C to 150 C air to air	1000 cyc	0/240
RSH	Ta=260C, 10 sec dwell	post stress	0/30
DPA	AEC Q101-004	post TC	0/6
DPA	AEC Q101-004	post H3TRB	0/6

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ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request. Contact Raja Roziah Raja Rahmat<Raja.Roziah.Rahmat@onsemi.com>

CHANGED PART IDENTIFICATION:

Affected products from ON Semiconductor with date code ww32 and greater may be sourced from either the ISMF Fab in Seremban (Malaysia) or the ZR Fab in Phoenix (USA).

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List of affected General Parts:

BYV32-200G	MUR840G	MURF860G
BYW29-200G BYW29-200H	MUR860G MUR860H	MURF860H MURH840CTG
BYW51-200G	MURB1620CTG	MURH860CTG
BYW80-200G	MURB1620CTRG	MURHB840CTG
MSR1560G	MURB1620CTRT4G	MURHB840CTT4
MSR860G	MURB1620CTT14G	MURHB840CTT4G
MSRD620CTG	MURB1620CTT4G	MURHB860CTT4G
MSRD620CTG	MURB1660CTG	MURHC860CTWP
MSRD620CTRG MSRD620CTT4	MURB1660CTT4G	MURHD560T4G
MSRD620CTT4G	MURC120WP	MURHD560W1T4G
MSRD620CTT4G	MURC1510WP	MURHF860CTG
MSRF1560G	MURC1520WP	NRVUB1620CTRT4
MSRF860G	MURC1540WP	NRVUB1620CTRT4G
MUR1510G	MURC1560WP	NRVUB1620CTT4
MUR1515G	MURC160WP	NRVUB1620CTT4G
MUR1520G	MURC240WP	NRVUD620CTG
MUR1540G	MURC3020WP	NRVUD620CTT4G
MUR1560G	MURC3040WP	NRVUS230T3G
MUR1560H	MURC820WP	SSRD8620CTT4G
MUR1610CTG	MURC860WP	SUR620CTT4G
MUR1615CTG	MURD305RL	SUR8115RLG
MUR1620CTG	MURD310T4	SUR81520G
MUR1620CTRG	MURD320T4	SUR81560G
MUR1640CTG	MURD320T4G	SUR8160RLG
MUR1640CTH	MURD330T4	SUR8460RLG
MUR1660CTG	MURD330T4G	SUR8820G
MUR2020RG	MURD340T4G	SUR8840G
MUR3020PTG	MURD530T4G	SURA8110T3G
MUR3020WTG	MURD550PFT4G	SURA8120T3G
MUR3040PTG	MURD610CTT4	SURA8130T3G
MUR3040WTG	MURD620CT1	SURA8140T3G
MUR3060PTG	MURD620CTG	SURA8160T3G
MUR3060WTG	MURD620CTH	SURA8210T3G
MUR550PFG	MURD620CTT4	SURA8215T3G
MUR620CTG	MURD620CTT4G	SURA8220T3G
MUR805G	MURF1560G	SURA8240T3G
MUR810G	MURF1620CTG	SURA8260T3G
MUR815G	MURF1660CTG	SURB1620CTT4
MUR820G	MURF550PFG	SURB1620CTT4G

SURC320PF SURD8320T4 SURD8320T4G SURD8330T4G SURHD8560T4G SURHS8160T3G SURS8340T3G SURS8360BT3G TURC160TR TURC160TR1



List of affected Customer Specific Parts:

SURB100CTT4

SURB100CTT4G

SURB121CTT4

SURB121CTT4G

SURC215-120WP

SURD106T4G

SURD107T4G

SURD5525PFT4G

SURF1620CT-SPG

TURC120TS1

TURC1310PF

TURC1310TR

TURC160TS1

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